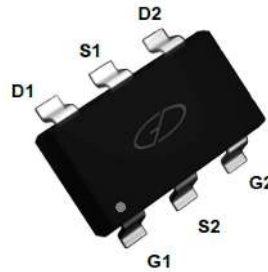
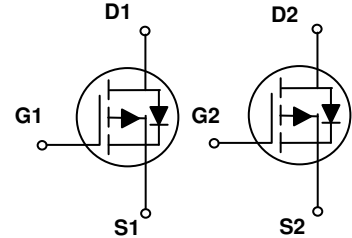


Main Product Characteristics

| | |
|---------------|------|
| $V_{(BR)DSS}$ | -20V |
| $R_{DS(ON)}$ | 85mΩ |
| I_D | -3A |



SOT-23-6L



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for hand-held devices, battery protection and load switch
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSF2215 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Rating | Unit |
|---|-----------|-------------|---------------------|
| Drain-Source Voltage | V_{DS} | -20 | V |
| Gate-Source Voltage | V_{GS} | ± 10 | V |
| Drain Current – Continuous ($T_A=25^\circ\text{C}$) | I_D | -3 | A |
| Drain Current – Continuous ($T_A=70^\circ\text{C}$) | | -2.4 | A |
| Drain Current – Pulsed ¹ | I_{DM} | -12 | A |
| Power Dissipation ($T_A=25^\circ\text{C}$) | P_D | 1.25 | W |
| Power Dissipation – Derate above 25°C | | 0.01 | W/ $^\circ\text{C}$ |
| Storage Temperature Range | T_{STG} | -55 to +150 | $^\circ\text{C}$ |
| Operating Junction Temperature Range | T_J | -55 to +150 | $^\circ\text{C}$ |

Thermal Characteristics

| Parameter | Symbol | Typ. | Max. | Unit |
|--|-----------------|------|------|--------------------|
| Thermal Resistance Junction to Ambient | $R_{\theta JA}$ | --- | 100 | $^\circ\text{C/W}$ |

Electrical Characteristics (T_J=25°C unless otherwise specified)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|---|-------------------------------------|---|------|------|------|-------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V, I _D =-250uA | -20 | --- | --- | V |
| BV _{DSS} Temperature Coefficient | ΔBV _{DSS} /ΔT _J | Reference to 25°C, I _D =-1mA | --- | 0.01 | --- | V/°C |
| Drain-Source Leakage Current | I _{DSS} | V _{DS} =-20V, V _{GS} =0V, T _J =25°C | --- | --- | -1 | uA |
| | | V _{DS} =-16V, V _{GS} =0V, T _J =125°C | --- | --- | -10 | |
| Gate-Source Leakage Current | I _{GSS} | V _{GS} =±10V, V _{DS} =0V | --- | --- | ±100 | nA |
| On Characteristics | | | | | | |
| Static Drain-Source On-Resistance | R _{DS(ON)} | V _{GS} =-4.5V, I _D =-3A | --- | 70 | 85 | mΩ |
| | | V _{GS} =-2.5V, I _D =-2A | --- | 95 | 120 | |
| | | V _{DS} =-1.8V, I _D =-1A | --- | 130 | 170 | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =0V, I _D =-250uA | -0.3 | -0.6 | -1.0 | V |
| V _{GS(th)} Temperature Coefficient | ΔV _{GS(th)} | | --- | 3 | --- | mV/°C |
| Forward Transconductance | g _{fs} | V _{DS} =10V, I _S =-1A | --- | 2.2 | --- | S |
| Dynamic and Switching Characteristics | | | | | | |
| Total Gate Charge ^{3, 4} | Q _g | V _{DS} =-10V, V _{GS} =-4.5V, I _D =-3A | --- | 4.8 | 8 | nC |
| Gate-Source Charge ^{3, 4} | Q _{gs} | | --- | 0.5 | 1 | |
| Gate-Drain Charge ^{3, 4} | Q _{gd} | | --- | 1.9 | 4 | |
| Turn-On Delay Time ^{3, 4} | T _{d(on)} | V _{DD} =-10V, V _{GS} =-4.5V, R _G =25Ω, I _D =-1A | --- | 3.5 | 7 | nS |
| Rise Time ^{3, 4} | T _r | | --- | 12.6 | 24 | |
| Turn-Off Delay Time ^{3, 4} | T _{d(off)} | | --- | 32.6 | 62 | |
| Fall Time ^{3, 4} | T _f | | --- | 8.4 | 16 | |
| Input Capacitance | C _{iss} | V _{DS} =-15V, V _{GS} =0V, F=1MHz | --- | 350 | 510 | pF |
| Output Capacitance | C _{oss} | | --- | 65 | 95 | |
| Reverse Transfer Capacitance | C _{rss} | | --- | 50 | 75 | |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| Continuous Source Current | I _S | V _G =V _D =0V, Force Current | --- | --- | -3 | A |
| Pulsed Source Current | I _{SM} | | --- | --- | -6 | A |
| Diode Forward Voltage | V _{SD} | V _{GS} =0V, I _S =-1A, T _J =25°C | --- | --- | -1 | V |

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300uS, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristics

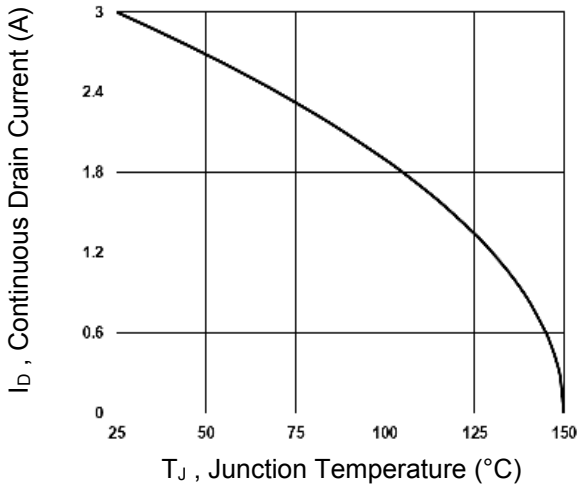


Fig.1 Continuous Drain Current vs. T_J

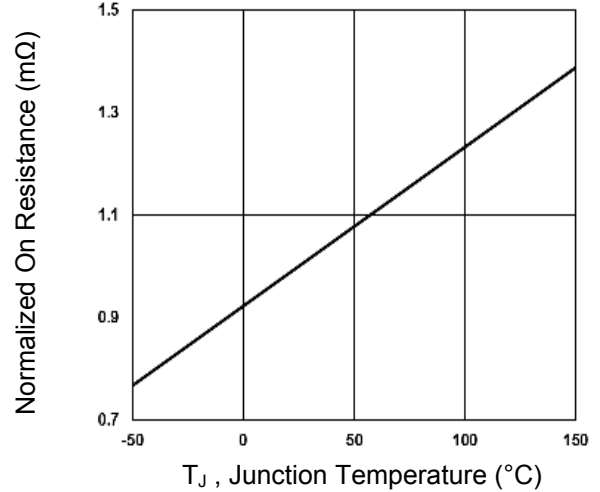


Fig.2 Normalized $R_{DS(ON)}$ vs. T_J

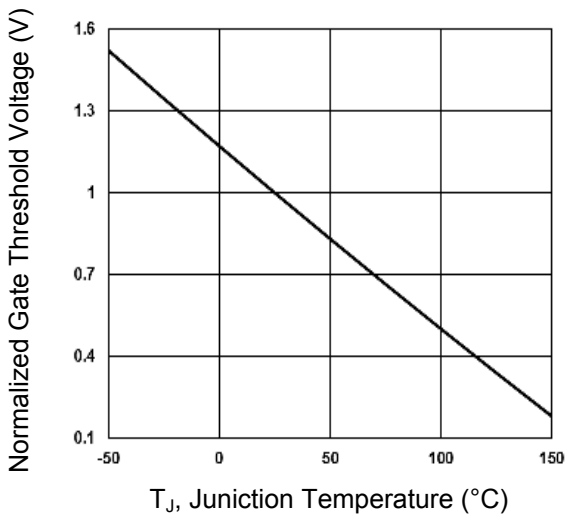


Fig.3 Normalized V_{th} vs. T_J

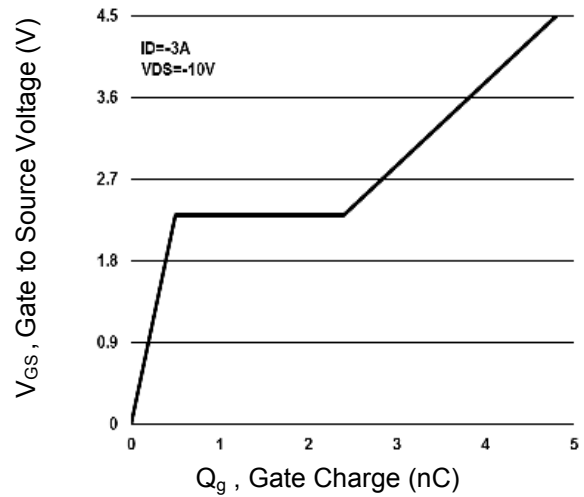


Fig.4 Gate Charge Waveform

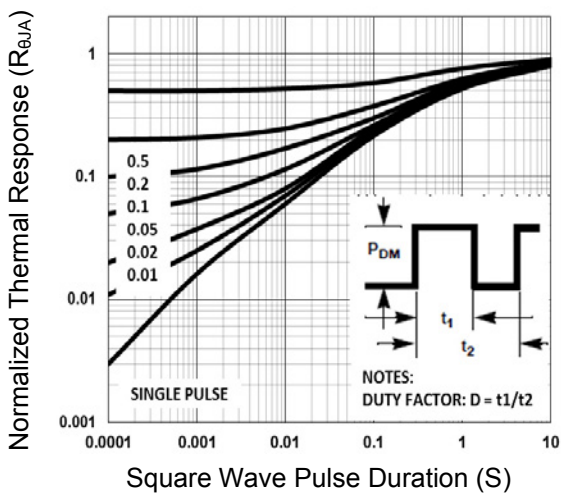


Fig.5 Normalized Transient Impedance

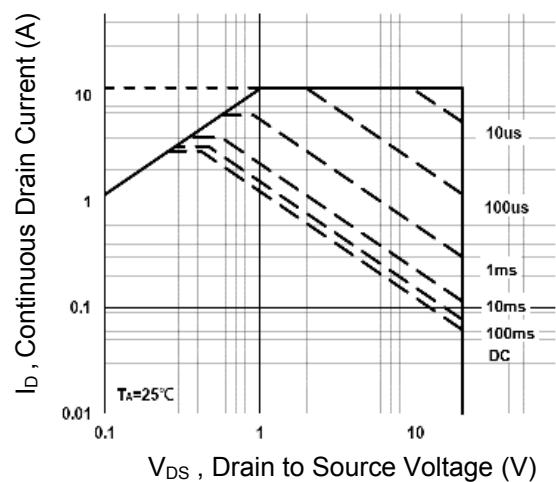


Fig.6 Maximum Safe Operation Area

Typical Electrical and Thermal Characteristics

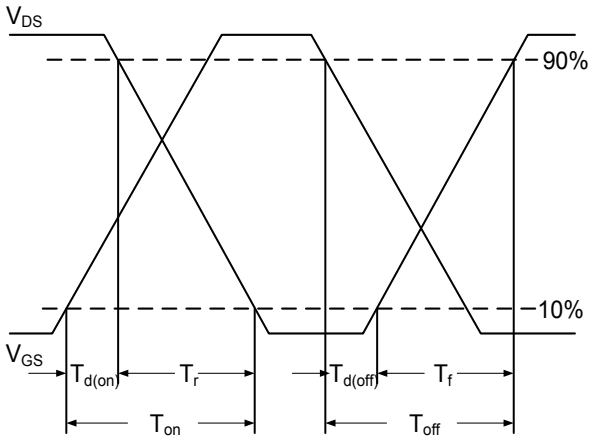


Fig.7 Switching Time Waveform

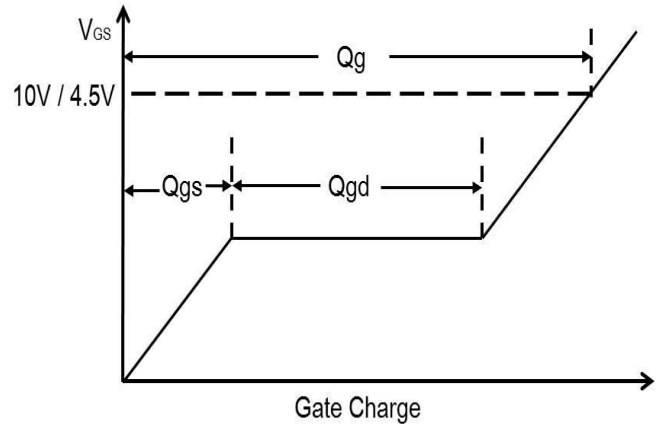
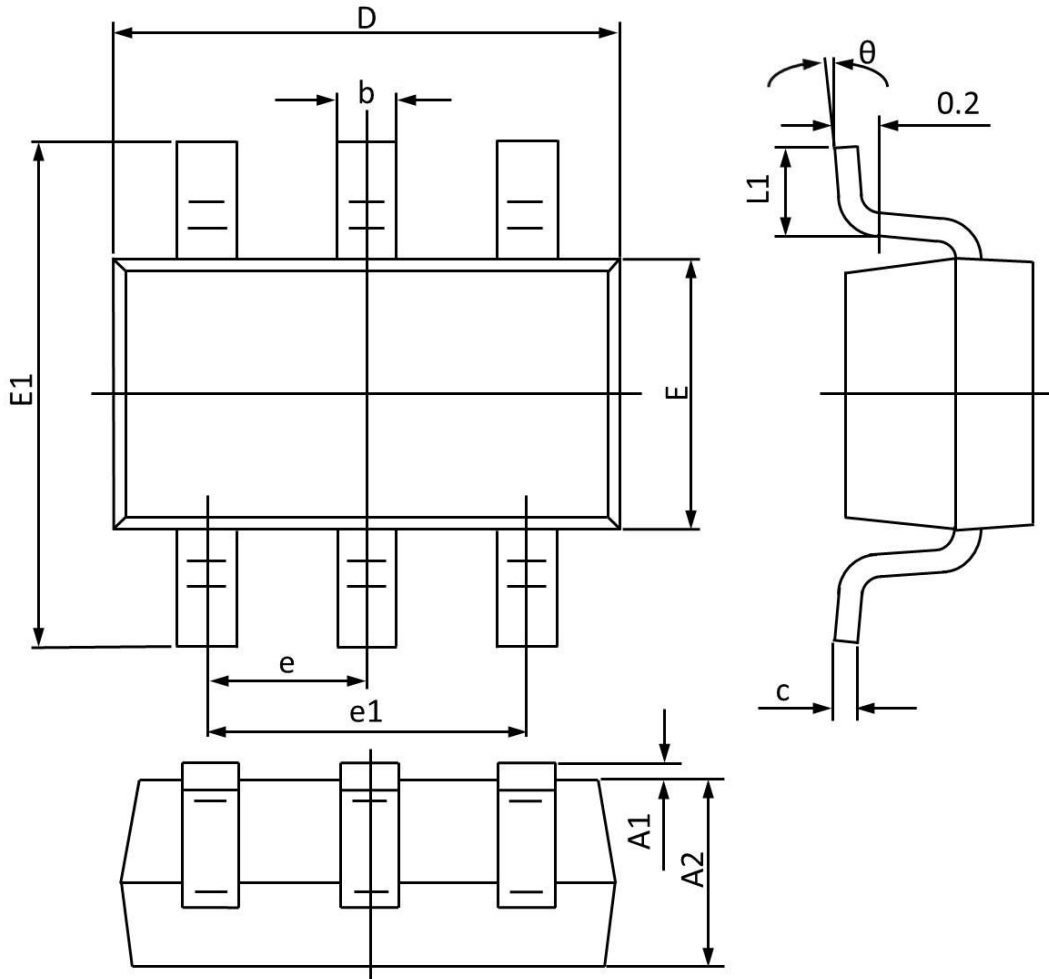


Fig.8 Gate Charge Waveform

Package Outline Dimensions

SOT-23-6L



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 |
| A2 | 1.000 | 1.200 | 0.040 | 0.047 |
| b | 0.300 | 0.500 | 0.012 | 0.019 |
| c | 0.047 | 0.207 | 0.002 | 0.008 |
| D | 2.800 | 3.000 | 0.110 | 0.118 |
| E | 1.500 | 1.800 | 0.059 | 0.070 |
| E1 | 2.600 | 3.000 | 0.103 | 0.118 |
| e | 0.950 TYP | | 0.037 TYP | |
| e1 | 1.900 TYP | | 0.075 TYP | |
| L1 | 0.250 | 0.550 | 0.010 | 0.021 |
| θ | 0° | 8° | 0° | 8° |